

SI4948EY-T1-E3-VB Datasheet Dual P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^{d, e}	Q _g (Typ.)			
- 60	0.054 at V _{GS} = - 10 V	- 5.3	17 nC			
	0.060 at V _{GS} = - 4.5 V	- 5.0	17 110			

FEATURES

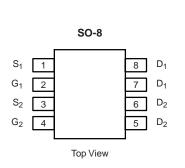
- · Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

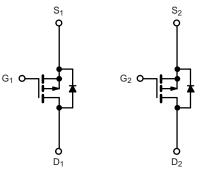


RoHS

APPLICATIONS

· Load Switches





P-Channel MOSFET

P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 60	V	
Gate-Source Voltage	V _{GS}	± 20	V	
	T _C = 25 °C		- 5.3 ^e	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	1 .	- 5.0 ^e	
Continuous Diam Curient (1) = 130 °C)	T _A = 25 °C	I _D	- 5.3 ^{a, b}	
	T _A = 70 °C		- 5.0 ^{a, b}	Α .
Pulsed Drain Current	I _{DM}	- 32 ^e	A	
	T _C = 25 °C	,	- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	- 2.0 ^{a, b}	
Avalanche Current	1 0.1 ml l	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		4.0	
Manianum Danian Disain ation	T _C = 70 °C		2.5	14/
Maximum Power Dissipation	T _A = 25 °C	P _D	2.0 ^{a, b}	W
	T _A = 70 °C	1	1.4 ^{a, b}	
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R_{thJF}	20	25	1	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on $T_C = 25 \, ^{\circ}C$.
- e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = -250 \mu\text{A}$	- 60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	In = - 250 µA		- 31		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0 1 1/1 1 0 1		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
D. I. O	_	V _{GS} = - 10 V, I _D = - 5 A		0.054			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 4.5 A		0.060		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 5 A		23		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1345		pF	
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		210			
Reverse Transfer Capacitance	C _{rss}			180			
Tatal Oats Observe	Q _g V _D	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -5 \text{ A}$		32	50	nC	
Total Gate Charge				15	25		
Gate-Source Charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$		4			
Gate-Drain Charge	Q_{gd}			7.5			
Gate Resistance	R _g	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	ì,	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		8	15		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		45	70		
Fall Time	t _f	j		12	25		
Turn-On Delay Time	t _{d(on)}			42	70	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		35	60		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	70		
Fall Time	t _f			16	30		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	Λ.	
Pulse Diode Forward Current	I _{SM}	-			- 32	A	
Body Diode Voltage	V _{SD}	I _S = -2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	- 55		34	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 0 A 31/4/4 400 A/4- T 05 00		22	40	nC	
Reverse Recovery Fall Time	t _a	$I_F = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °\text{C}$		11		ns	
Reverse Recovery Rise Time	t _b			23			

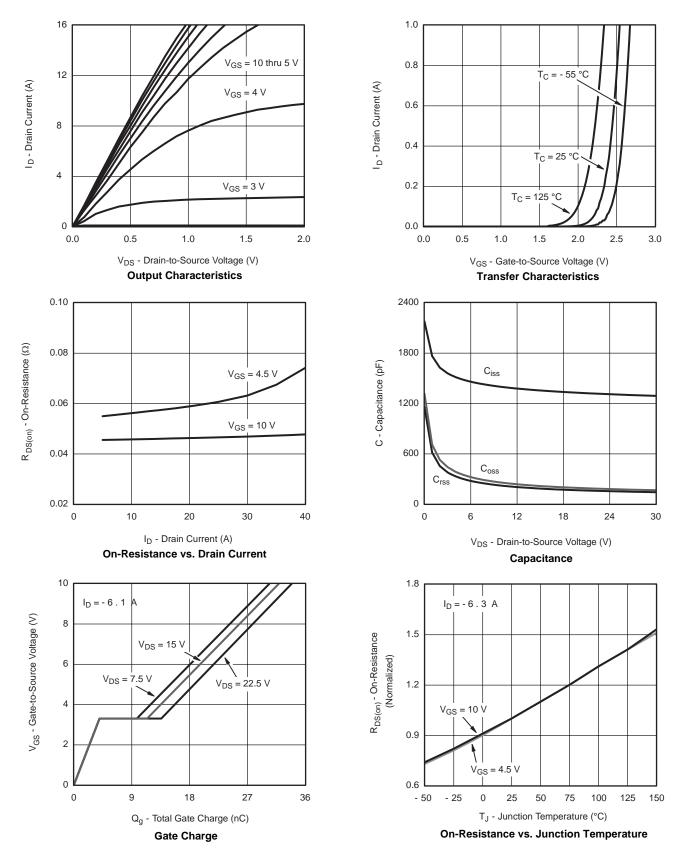
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

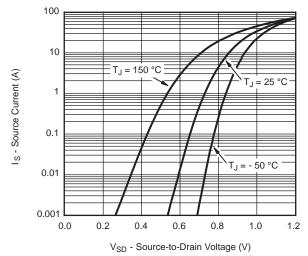


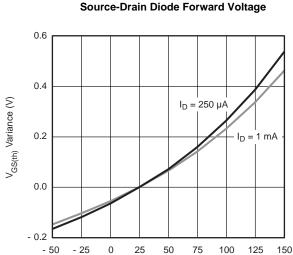
TYPICAL CHARACTERISTICS 25 C, unless otherwise noted



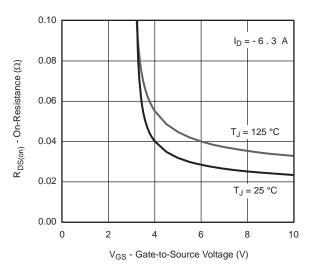


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

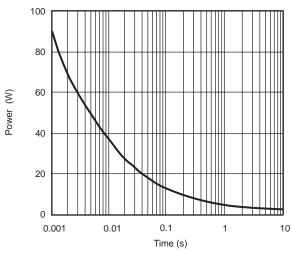




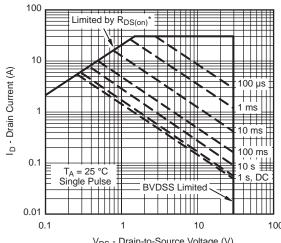
T_J - Temperature (°C) Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



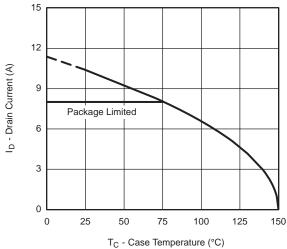
V_{DS} - Drain-to-Source Voltage (V)

Safe Operating Area

^{*} V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



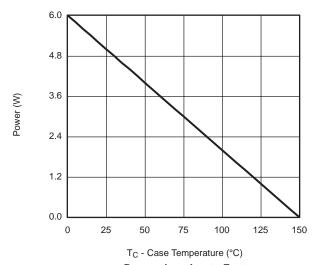
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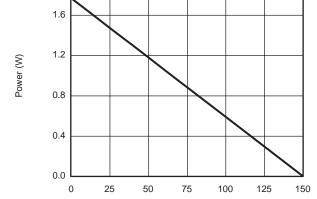




2.0







T_A - Ambient Temperature (°C) Power Derating, Junction-to-Ambient

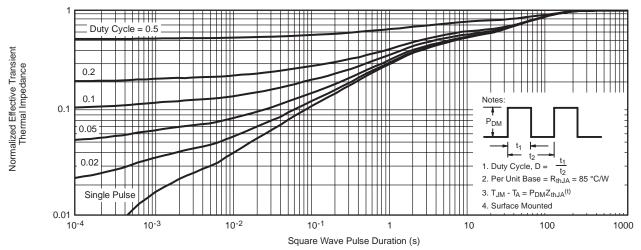
服务热线:400-655-8788

Power, Junction-to-Foot

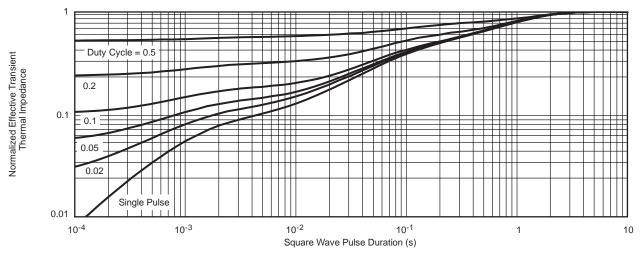
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS		INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev I 11-Sen-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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